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PTO/SB/21 (08-00)

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TRANSMITTAL FORM

(to be used for all correspondence after initial filing)

Total Number of Pages in This Submission

Application Number	10/072,931		
Filing Date	February 12, 2002		
First Named Inventor	Shunpei YAMAZAKI et al.		
Group Art Unit	2812		
Examiner Name	S. Isaac		
Attorney Docket Number	0756-2344		

ENCLOSURES (check all that apply)							
Fee Transmittal Form Fee Attached Amendment / Reply After Final Affidavits/declaration(s Extension of Time Reques Express Abandonment Re Information Disclosure Sta Certified Copy of Priority Document(s) Response to Missing Parts Incomplete Application Response to Missing F under 37 CFR 1.52 or	quest tement	Assignment Papers (for an Application) Drawing(s) Declaration and Power of Attorney Licensing-related Papers Petition Petition Power of Attorney, Revocation Change of Correspondence Address Terminal Disclaimer Request for Refund CD, Number of CD(s) After Allowance Communication to Group Appeal Communication to Group (Appeal Notice, Brief, Reptit Brief) Proprietary Information Status Letter Other Enclosures 1. 2. 3. 4. TERM 2800 Remarks The Commissioner is hereby authorized to charge any additional fees required or credit any overpayments to Deposit Account No. 50-2280 for the above identified docket number.					
SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT Eric J. Robinson, Reg. No. 38,285 Robinson Intellectual Property Law Office, P.C. PMB 955 Individual name 21010 Southbank Street Potomac Falls, VA 20165							
Signature	Signature 5						
Date March 19, 2003							
CERTIFICATE OF MAILING							
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Type or printed name	Type or printed name Adele M. Stamper						

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Date

March 19, 2003

PTO/SB/17 (11-00) Approved for use through 10/31/2002. OMB 0651-0032

Complete if Known

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TRANSMITTAL		Filing Date		February 12, 2002						
FOR FY 2003		First Named Inventor		Shunpei YAMAZAKI et al.						
MAR 2 4 2003 July OR T 1 2003		Examiner Name		S. Isaac						
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**or number previously paid, if greater; For Reissues, see above Name: Adele M. Stamper										
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	Eric J. Robinson	T	Regi	istration	No.	38,	285	-	(571) 434-678	9
Name (Print/Type)			(Atto	rney/Ag	ent)			Telephone		
Signature		2	••					Date	March 19, 20	03

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Name: Adele M. Stamper

AMENDMENT & RESPONSE TO RESTRICTION REQUIREMENT

Honorable Commissioner of Patents

Washington, D.C. 20231

Sir:

In response to the Office Action of February 19, 2003, please amend the subject application as follows:

IN THE CLAIMS:

Please amend claims 47, 66, and 67 as follows:

semiconductor Sdevice 47. (Amended) A method of manufacturing a comprising:

forming a first semiconductor film having an amorphous structure over a substrate;

providing the first semiconductor film with a material for promoting crystallization; heating the first semiconductor film for crystallizing;

irradiating the first semiconductor film with a laser light for improving crystallinity;

forming a barrier layer over the first semiconductor film having crystalline structure:

forming a second semiconductor film over the barrier layer;

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